



Final Product/Process Change Notification

Document #:FPCN22647XO

Issue Date:27 Dec 2019

Title of Change:	EMC Change for the devices which use Samsung SDI EMC- Dual Source All of affected pkg.	
Proposed First Ship date:	03 Apr 2020 or earlier if approved by customer	
Contact Information:	Contact your local ON Semiconductor Sales Office or Daisy.Zhi@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Lake.Wang@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Marking of parts no change and traceability of change with Product date code.	
Change Category:	Assembly Change	
Change Sub-Category(s):	Material Change	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
ON Semiconductor Suzhou, China	None	
Description and Purpose:		
ON Semiconductor wishes to inform our customers of a change in mold compounds used for the devices listed in this PCN. This is the final product change notification (FPCN) of IPCN22647. This change is a result of an End of Life notification received from Samsung for several of their SDI Mold Compounds. Due to the discontinuance of the SDI mold compounds, ON Semiconductor will only have limited supplies of the existing material and in some cases this may not allow for the normal change notification period. All other aspects of the impacted products (form, fit, function) will remain unchanged.		
	Before Change Description	After Change Description
Mold Compound	SI7200DX2; Supplier: Samsung SDI	KTMC1050GFB, Supplier : KCC
	SD8200DL; Supplier: Samsung SDI	KTMC1050GFA, Supplier : KCC

**Reliability Data Summary:****QV DEVICE NAME:** KSC5603DTU (PTI : FD)**RMS** : U56675**PACKAGE** : TO-220

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	TA = 150°C for 1008 hours, 80% rated	1008 hrs	0/77
HTSL	JESD22-A103	TA = 150°C for 1008 hours	1008 hrs	0/77
TC	JESD22-A104	Temp = -55°C to +150°C for 1000 cycles	1000 cyc	0/77
HAST	JESD22-A110	Temp= +110°C, RH=85%, bias = 80% of rated BV or 100V max	264 hrs	0/77
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/10
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/15
Tri-Temp		Tri-Temperature, Per 48A		0/30
TR		Provide thermal comparison data to ensure spec compliance		0/10
PD		Per Case Outline		0/10

QV DEVICE NAME: FYP2010DNTU (PTI : FB)**RMS** : U56685**PACKAGE** : TO-220

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	TA = 150°C for 1008 hours, 80% rated	1008 hrs	0/77
HTSL	JESD22-A103	TA = 150°C for 1008 hours	1008 hrs	0/77
TC	JESD22-A104	Temp = -55°C to +150°C for 1000 cycles	1000 cyc	0/77
H3TRB	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	1008 hrs	0/77
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/10
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/15
Tri-Temp		Tri-Temperature, Per 48A		0/30
TR		Provide thermal comparison data to ensure spec compliance		0/10
PD		Per Case Outline		0/10

QV DEVICE NAME: FQA11N90-F109**RMS** : U56634**PACKAGE** : TO3P

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta = 150°C for device, bias = 80% of max rated	1008 hrs	0/154
HTGB	JESD22-A108	Ta = 150°C for 1008 hours, 100% rated Vgs	1008 hrs	0/154
HTSL	JESD22-A103	Ta = 150°C for 1008 hours	1008 hrs	0/154
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cyc	0/154
HAST	JESD22-A110	Temp= +130°C, RH=85% , bias = 80% of rated or 100V max	96 hrs	0/154
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/20
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/30
PD		Per Case Outline		0/20
Tri-temp		Tri-Temp Characterization, Per 48A		0/60
TR		Thermal Resistance		0/20



QV DEVICE NAME: RHRG75120

RMS : U56686

PACKAGE : TO247

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta = 175°C for device, bias = 80% of max rated	1008 hrs	0/77
HTSL	JESD22-A103	Ta = 175°C for 1008 hours	1008 hrs	0/77
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cyc	0/77
H3TRB	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	1008 hrs	0/77
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/10
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/15
PD		Per Case Outline		0/10
Tri-temp		Tri-Temp Characterization, Per 48A		0/30
TR		Thermal Resistance		0/10

QV DEVICE NAME: FCH041N60F-F085

RMS : U56699

PACKAGE : TO247

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta = 150°C for device, bias = 100% of max rated	1008 hrs	0/231
HTGB	JESD22-A108	Ta = 150°C for 1008 hours, 100% rated Vgs	1008 hrs	0/231
HTSL	JESD22-A103	Ta = 150°C for 1008 hours	1008 hrs	0/231
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cyc	0/231
IOL	MIL STD750, M 1037 AEC Q101	Ta=+25°C, delta Tj=100°C max, Ton=Toff is 3.5min	8572Cyc	0/231
HAST	JESD22 A110	Temp= +110°C, RH=85% , 264hr, bias = 80% of rated V or 100V max	264hrs	0/231
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/30
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/45
PD		Per Case Outline		0/30
Tri-temp		Tri-Temp Characterization, Per 48A		0/90
TR		Thermal Resistance		0/30
CDPA TCDT	AEC Q101, rev D, test 7A (alt)	Custom Destructive Physical Analysis - TC Delamination Test, Post 1000 cyc TC		0/66
CDPA SAT	AEC-006	Post HTRB,HTGB		0/66
DPA	AEC-Q101-004 Section 4	Destructive Physical Analysis Post TC, HAST, HTRB, HTGB		0/6
CDPA WP BS	MIL 883E, AEC -006	Custom Destructive Physical Analysis - Wire Pull, Ball Shear Post TC, HTRB, HTGB		0/18
CDPA X Section	AEC -006	Post TC, HTRB, HTGB		0/9
Shift		Shift Analysis for HTRB/HTGB/HTSL/TC/IOL/HAST		Pass

**QV DEVICE NAME:** FDP12N60NZ**RMS** : U56667**PACKAGE** : TO-220

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	TA = 150°C for 1008 hours, 80% rated	1008 hrs	0/77
HTGB	JESD22-A108	TA = 150 °C for 1008 hours, 100% rated Vgs	1008 hrs	0/77
HTSL	JESD22-A103	TA = 150°C for 1008 hours	1008 hrs	0/77
TC	JESD22-A104	Temp = -55°C to +150°C for 1000 cycles	1000 cyc	0/77
HAST	JESD22-A110	Temp= +130°C, RH=85%, bias = 80% of rated BV or 100V max	96 hrs	0/77
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/10
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/15
Tri-Temp		Tri-Temperature, Per 48A		0/30
TR		Provide thermal comparison data to ensure spec compliance		0/10
PD		Per Case Outline		0/10

QV DEVICE NAME: FGY160T65SPD-F085**RMS** : U56679**PACKAGE** : TP247

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta = 175°C for device, bias = 100% of max rated	1008 hrs	0/231
HTGB	JESD22-A108	Ta = 175°C for 1008 hours, 100% rated Vgs	1008 hrs	0/231
HTSL	JESD22-A103	Ta = 175°C for 1008 hours	1008 hrs	0/231
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cyc	0/231
IOL	MIL STD750, M 1037 AEC Q101	Ta=+25°C, delta Tj=100°C max, Ton=Toff is 3.5min	8572Cyc	0/231
H3TRB	JESD22-A101	Temp = 85°C, RH=85%, bias = 80% of rated V or 100V max	1008hrs	0/231
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/30
SD	J STD 002B	Ta=245°C 5 sec dwell	5s	0/45
PD		Per Case Outline		0/30
CDPA TCDT	AEC Q101, rev D, test 7A (alt)	Custom Destructive Physical Analysis - TC Delamination Test, Post 1000 cyc TC		0/66
CDPA SAT	AEC-006	Post HTRB,HTGB		0/66
DPA	AEC-Q101-004 Section 4	Destructive Physical Analysis Post TC, H3TRB, HTRB, HTGB		0/6
CDPA WP BS	MIL 883E, AEC -006	Custom Destructive Physical Analysis - Wire Pull, Ball Shear Post TC, HTRB, HTGB		0/18
CDPA X Section	AEC -006	Post TC, HTRB, HTGB		0/9

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).



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Part Number	Qualification Vehicle
FDH50N50-F133	FCH041N60F-F085
FDH45N50F-F133	FCH041N60F-F085
FDH3632	FCH041N60F-F085
FDH047AN08A0	FCH041N60F-F085
BDW94C	KSC5603DTU
KSC5603DTU	KSC5603DTU
KSA1010YTU	KSC5603DTU
FJP5027RTU	KSC5603DTU
KSC2073TU	KSC5603DTU
FJP5555TU	KSC5603DTU
HUF75344G3	FCH041N60F-F085
FQH44N10-F133	FCH041N60F-F085
FCH35N60	FCH041N60F-F085
FCH170N60	FCH041N60F-F085
FCH130N60	FCH041N60F-F085
FCH072N60	FCH041N60F-F085
FCH041N60F	FCH041N60F-F085
FCH041N60E	FCH041N60F-F085
ISL9R30120G2	RHRG75120
FFH30US30DN	RHRG75120
FFH50US60S	RHRG75120
RURG80100	RHRG75120
RURG1520CC	RHRG75120
RHRG3060CC	RHRG75120
RURG3020CC	RHRG75120
RURG3060CC	RHRG75120
RHRG3060	RHRG75120
RHRG1560CC	RHRG75120
ISL9R18120G2	RHRG75120
ISL9K1560G3	RHRG75120
FFH75H60S	RHRG75120
FFH60UP40S	RHRG75120
FFA60UP30DNTU	FQA11N90-F109



MBRP1545NTU	FYP2010DNTU
MBRP3045NTU	FYP2010DNTU
MBRP3010NTU	FYP2010DNTU
FYP2010DNTU	FYP2010DNTU
FYP2006DNTU	FYP2010DNTU
FYP1010DNTU	FYP2010DNTU
KSC2073H2TU	KSC5603DTU
KSB596YTU	KSC5603DTU
KSD526Y	KSC5603DTU
KSC5338DTU	KSC5603DTU
KSD880O	KSC5603DTU
BDW93C	KSC5603DTU
KSD526YTU	KSC5603DTU
KSC5021RTU	KSC5603DTU
BD239CTU	KSC5603DTU
BD244A	KSC5603DTU
FJP13009TU	KSC5603DTU
KSC5027OTU	KSC5603DTU
BUT11A	KSC5603DTU
FJP5304DTU	KSC5603DTU
KSD363YTU	KSC5603DTU
FJP3305H1TU	KSC5603DTU
KSD363RTU	KSC5603DTU
KSC5338D	KSC5603DTU
KSD880YTU	KSC5603DTU
KSC2334YTU	KSC5603DTU
KSA940TU	KSC5603DTU
KSD560YTU	KSC5603DTU
FGH20N60SFDTU	FGY160T65SPD-F085
FGH40N60SFTU	FGY160T65SPD-F085
FGH40N60SFDTU	FGY160T65SPD-F085
FGH30N60LSDTU	FGY160T65SPD-F085
HGTG30N60C3D	FGY160T65SPD-F085
FGA20S140P	FQA11N90-F109



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FGA30S120P	FQA11N90-F109
FQA9N90C-F109	FQA11N90-F109
FQA11N90-F109	FQA11N90-F109
FQA11N90C-F109	FQA11N90-F109
FQP9N50C	FDP12N60NZ
FQP8N60C	FDP12N60NZ
FQP13N50C	FDP12N60NZ
FQP11N40C	FDP12N60NZ
IRF634B-FP001	FDP12N60NZ
FQP12N60C	FDP12N60NZ
HUF75639G3	FCH041N60F-F085
KSC2334Y	KSC5603DTU
FJP3305H2TU	KSC5603DTU
KSB546YTU	KSC5603DTU

Japanese translation of the notification starts here.
通知の日本語訳はここから始まります。

Note: *The Japanese version is for reference only. In case of any differences between the English and Japanese version, the English version shall control.*

注：日本語版は参照用です。英語版と日本語版の違いがある場合は、英語版が優先されます。



最終製品 / プロセス変更通知

文書番号# : FPCN22647XO

発行日: 27 Dec 2019

変更件名:	Samsung SDI 製モールドコンパウンドを使用する製品のモールドコンパウンド変更-デュアルソースで影響を受けるすべてのパッケージ	
初回出荷予定日:	04 Apr 2020 またはお客様からの承認が得られた場合はそれ以前.	
連絡先情報	現地のオン・セミコンダクター営業所または <Daisy.Zhi@onsemi.com> にお問い合わせください。	
サンプル:	現地のオン・セミコンダクター営業所または <PCN.Samples@onsemi.com> にお問い合わせください。 サンプルは、この変更の初回通知、初回 PCN の日付から 30 日以内に要求してください。 サンプル納入時は、依頼日、数量、特別梱包材/ラベル条件によって異なります。	
追加の信頼性データ:	お客さまの地域のオン・セミコンダクター営業所または <Lake.Wang@onsemi.com> にお問い合わせください。	
通知種別:	これは、お客様宛の最終製品 / プロセス変更通知 (FPCN) です。FPCN は、変更実施の 90 日前に発行されます。 オン・セミコンダクターは、この通知の送付から 30 日以内に書面による問い合わせがない限り、この変更が承諾されたものとみなします。 お問い合わせは、<PCN.Support@onsemi.com> 宛てにお願いします。	
変更部品の識別:	製品のマーキングに変更なし、そして製品の日付コードで変更が追跡されます。	
変更カテゴリ: 組立変更		
変更サブカテゴリ: 素材の変更		
影響を受ける拠点:		
オン・セミコンダクター拠点:	外部製造工場 / 下請業者拠点:	
ON Semiconductor Suzhou, China	無し	
説明および目的:		
オン・セミコンダクターは、本FPCNに記載された製品に使用するモールド コンパウンドの変更をお客様にお知らせいたします。これは、IPC22647の最終製品変更通知 (FPCN) です。この変更は、サムソンSDIから受けたいくつかの モールド コンパウンドの生産終了の通知によるものです。SDI モールド コンパウンドの廃止によって、オン・セミコンダクターでは既存の材料の供給が限定されるようになるため、場合によっては、通常の変更通知期間の確保が不可能になる場合があります。対象となる製品の他の特徴 (形状、適合性、機能) に変更はありません。		
	変更前の表記	変更後の表記
モールド・コンパウンド	SI7200DX2; Supplier: Samsung SDI	KTMC1050GFB, Supplier : KCC
	SD8200DL; Supplier: Samsung SDI	KTMC1050GFA, Supplier : KCC



信頼性データの要約:

デバイス名: KSC5603DTU (PTI : FD)

RMS: U56675

パッケージ: TO-220

テスト	仕様	条件	間隔	結果
HTRB	JESD22-A108	TA = 150°C for 1008 hours, 80% rated	1008 hrs	0/77
HTSL	JESD22-A103	TA = 150°C for 1008 hours	1008 hrs	0/77
TC	JESD22-A104	Temp = -55°C to +150°C for 1000 cycles	1000 cyc	0/77
HAST	JESD22-A110	Temp = +110°C, RH=85%, bias = 80% of rated BV or 100V max	264 hrs	0/77
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/10
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/15
Tri-Temp		Tri-Temperature, Per 48A		0/30
TR		Provide thermal comparison data to ensure spec compliance		0/10
PD		Per Case Outline		0/10

デバイス名: FYP2010DNTU (PTI : FB)

RMS: U56685

パッケージ: TO-220

テスト	仕様	条件	間隔	結果
HTRB	JESD22-A108	TA = 150°C for 1008 hours, 80% rated	1008 hrs	0/77
HTSL	JESD22-A103	TA = 150°C for 1008 hours	1008 hrs	0/77
TC	JESD22-A104	Temp = -55°C to +150°C for 1000 cycles	1000 cyc	0/77
H3TRB	JESD22-A101	Temp = 85°C, RH=85%, bias = 80% of rated V or 100V max	1008 hrs	0/77
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/10
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/15
Tri-Temp		Tri-Temperature, Per 48A		0/30
TR		Provide thermal comparison data to ensure spec compliance		0/10
PD		Per Case Outline		0/10

デバイス名: FQA11N90-F109

RMS: U56634

パッケージ: TO3P

テスト	仕様	条件	間隔	結果
HTRB	JESD22-A108	Ta = 150°C for device, bias = 80% of max rated	1008 hrs	0/154
HTGB	JESD22-A108	Ta = 150°C for 1008 hours, 100% rated Vgs	1008 hrs	0/154
HTSL	JESD22-A103	Ta = 150°C for 1008 hours	1008 hrs	0/154
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cyc	0/154
HAST	JESD22-A110	Temp = +130°C, RH=85%, bias = 80% of rated or 100V max	96 hrs	0/154
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/20
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/30
PD		Per Case Outline		0/20
Tri-temp		Tri-Temp Characterization, Per 48A		0/60
TR		Thermal Resistance		0/20



デバイス名: RHRG75120

RMS : U56686

パッケージ: TO247

テスト	仕様	条件	間隔	結果
HTRB	JESD22-A108	Ta = 175°C for device, bias = 80% of max rated	1008 hrs	0/77
HTSL	JESD22-A103	Ta = 175°C for 1008 hours	1008 hrs	0/77
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cyc	0/77
H3TRB	JESD22-A101	Temp = 85C, RH=85%, bias = 80% of rated V or 100V max	1008 hrs	0/77
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/10
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/15
PD		Per Case Outline		0/10
Tri-temp		Tri-Temp Characterization, Per 48A		0/30
TR		Thermal Resistance		0/10

デバイス名: FCH041N60F-F085

RMS : U56699

パッケージ: TO247

テスト	仕様	条件	間隔	結果
HTRB	JESD22-A108	Ta = 150°C for device, bias = 100% of max rated	1008 hrs	0/231
HTGB	JESD22-A108	Ta = 150°C for 1008 hours, 100% rated Vgs	1008 hrs	0/231
HTSL	JESD22-A103	Ta = 150°C for 1008 hours	1008 hrs	0/231
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cyc	0/231
IOL	MIL STD750, M 1037 AEC Q101	Ta=+25°C, delta Tj=100°C max, Ton=Toff is 3.5min	8572Cyc	0/231
HAST	JESD22 A110	Temp= +110°C, RH=85% , 264hr, bias = 80% of rated V or 100V max	264hrs	0/231
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/30
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/45
PD		Per Case Outline		0/30
Tri-temp		Tri-Temp Characterization, Per 48A		0/90
TR		Thermal Resistance		0/30
CDPA TCDT	AEC Q101, rev D, test 7A (alt)	Custom Destructive Physical Analysis - TC Delamination Test, Post 1000 cyc TC		0/66
CDPA SAT	AEC-006	Post HTRB, HTGB		0/66
DPA	AEC-Q101-004 Section 4	Destructive Physical Analysis Post TC, HAST, HTRB, HTGB		0/6
CDPA WP BS	MIL 883E, AEC -006	Custom Destructive Physical Analysis - Wire Pull, Ball Shear Post TC, HTRB, HTGB		0/18
CDPA X Section	AEC -006	Post TC, HTRB, HTGB		0/9
Shift		Shift Analysis for HTRB/HTGB/HTSL/TC/IOL/HAST		Pass



デバイス名: FDP12N60NZ

RMS : U56667

パッケージ : TO-220

テスト	仕様	条件	間隔	結果
HTRB	JESD22-A108	TA = 150°C for 1008 hours, 80% rated	1008 hrs	0/77
HTGB	JESD22-A108	TA = 150 °C for 1008 hours, 100% rated Vgs	1008 hrs	0/77
HTSL	JESD22-A103	TA = 150°C for 1008 hours	1008 hrs	0/77
TC	JESD22-A104	Temp = -55°C to +150°C for 1000 cycles	1000 cyc	0/77
HAST	JESD22 A110	Temp= +130°C, RH=85%, bias = 80% of rated BV or 100V max	96 hrs	0/77
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/10
SD	J STD 002	Ta=245°C 5 sec dwell	5s	0/15
Tri-Temp		Tri-Temperature, Per 48A		0/30
TR		Provide thermal comparison data to ensure spec compliance		0/10
PD		Per Case Outline		0/10

デバイス名: FGY160T65SPD-F085

RMS : U56679

パッケージ : TP247

テスト	仕様	条件	間隔	結果
HTRB	JESD22-A108	Ta = 175°C for device, bias = 100% of max rated	1008 hrs	0/231
HTGB	JESD22-A108	Ta = 175°C for 1008 hours, 100% rated Vgs	1008 hrs	0/231
HTSL	JESD22-A103	Ta = 175°C for 1008 hours	1008 hrs	0/231
TC	JESD22-A104	Temp = -55°C to +150°C; for 1000 cycles	1000 cyc	0/231
IOL	MIL STD750, M 1037 AEC Q101	Ta=+25°C, delta Tj=100°C max, Ton=Toff is 3.5min	8572Cyc	0/231
H3TRB	JESD22-A101	Temp = 85°C, RH=85%, bias = 80% of rated V or 100V max	1008hrs	0/231
RSH	JESD22-B106	265 °C Immersion and 10s	10s	0/30
SD	J STD 002B	Ta=245°C 5 sec dwell	5s	0/45
PD		Per Case Outline		0/30
CDPA TCDT	AEC Q101, rev D, test 7A (alt)	Custom Destructive Physical Analysis - TC Delamination Test, Post 1000 cyc TC		0/66
CDPA SAT	AEC-006	Post HTRB, HTGB		0/66
DPA	AEC-Q101-004 Section 4	Destructive Physical Analysis Post TC, H3TRB, HTRB, HTGB		0/6
CDPA WP BS	MIL 883E, AEC -006	Custom Destructive Physical Analysis - Wire Pull, Ball Shear Post TC, HTRB, HTGB		0/18
CDPA X Section	AEC -006	Post TC, HTRB, HTGB		0/9

**電気的特性の要約:**

電気的特性は影響を受けません。

影響を受ける部品の一覧:

注: 部品一覧には標準部品番号 (既製品) のみが記載されています。本 PCN の影響を受けるカスタム部品番号は、PCN メールで提供される顧客個別の付録、または PCN カスタマイズポータルに記載されています。

部品番号	認定試験用ピークル
FDH50N50-F133	FCH041N60F-F085
FDH45N50F-F133	FCH041N60F-F085
FDH3632	FCH041N60F-F085
FDH047AN08A0	FCH041N60F-F085
BDW94C	KSC5603DTU
KSC5603DTU	KSC5603DTU
KSA1010YTU	KSC5603DTU
FJP5027RTU	KSC5603DTU
KSC2073TU	KSC5603DTU
FJP5555TU	KSC5603DTU
HUF75344G3	FCH041N60F-F085
FQH44N10-F133	FCH041N60F-F085
FCH35N60	FCH041N60F-F085
FCH170N60	FCH041N60F-F085
FCH130N60	FCH041N60F-F085
FCH072N60	FCH041N60F-F085
FCH041N60F	FCH041N60F-F085
FCH041N60E	FCH041N60F-F085
ISL9R30120G2	RHRG75120
FFH30US30DN	RHRG75120
FFH50US60S	RHRG75120
RURG80100	RHRG75120
RURG1520CC	RHRG75120
RHRG3060CC	RHRG75120
RURG3020CC	RHRG75120
RURG3060CC	RHRG75120
RHRG3060	RHRG75120
RHRG1560CC	RHRG75120



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ISL9R18120G2	RHRG75120
ISL9K1560G3	RHRG75120
FFH75H60S	RHRG75120
FFH60UP40S	RHRG75120
FFA60UP30DNTU	FQA11N90-F109
MBRP1545NTU	FYP2010DNTU
MBRP3045NTU	FYP2010DNTU
MBRP3010NTU	FYP2010DNTU
FYP2010DNTU	FYP2010DNTU
FYP2006DNTU	FYP2010DNTU
FYP1010DNTU	FYP2010DNTU
KSC2073H2TU	KSC5603DTU
KSB596YTU	KSC5603DTU
KSD526Y	KSC5603DTU
KSC5338DTU	KSC5603DTU
KSD880O	KSC5603DTU
BDW93C	KSC5603DTU
KSD526YTU	KSC5603DTU
KSC5021RTU	KSC5603DTU
BD239CTU	KSC5603DTU
BD244A	KSC5603DTU
FJP13009TU	KSC5603DTU
KSC5027OTU	KSC5603DTU
BUT11A	KSC5603DTU
FJP5304DTU	KSC5603DTU
KSD363YTU	KSC5603DTU
FJP3305H1TU	KSC5603DTU
KSD363RTU	KSC5603DTU
KSC5338D	KSC5603DTU
KSD880YTU	KSC5603DTU
KSC2334YTU	KSC5603DTU
KSA940TU	KSC5603DTU
KSD560YTU	KSC5603DTU
FGH20N60SFDTU	FGY160T65SPD-F085
FGH40N60SFTU	FGY160T65SPD-F085
FGH40N60SFDTU	FGY160T65SPD-F085



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FGH30N60LSDTU	FGY160T65SPD-F085
HGTG30N60C3D	FGY160T65SPD-F085
FGA20S140P	FQA11N90-F109
FGA30S120P	FQA11N90-F109
FQA9N90C-F109	FQA11N90-F109
FQA11N90-F109	FQA11N90-F109
FQA11N90C-F109	FQA11N90-F109
FQP9N50C	FDP12N60NZ
FQP8N60C	FDP12N60NZ
FQP13N50C	FDP12N60NZ
FQP11N40C	FDP12N60NZ
IRF634B-FP001	FDP12N60NZ
FQP12N60C	FDP12N60NZ
HUF75639G3	FCH041N60F-F085
KSC2334Y	KSC5603DTU
FJP3305H2TU	KSC5603DTU
KSB546YTU	KSC5603DTU